

ABSTRACT

A semiconductor device fabricating method comprises a substrate forming step of forming a plurality of separate conductive pads 20 on an adhesive layer included in an adhesive sheet 50, and a semiconductor chip mounting step of bonding semiconductor chips to the adhesive sheet 50 with surfaces thereof not provided with any electrodes in contact with the adhesive sheet 50, and electrically connecting electrodes 11 formed on the semiconductor chips 10 and upper parts of the conductive pads 20 with wires 30. The semiconductor chips 10, the wires 30 and the conductive pads 20 are sealed in a sealing resin molding 40, and then the adhesive sheet 50 is separated from the sealing resin molding 40. Each of the conductive pads 20 has a reduced part 20b, and a jutting part 20a jutting out from the reduced part 20b. The conductive pads 20 having such construction can be firmly bonded to the sealing resin molding 40.